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y. Steptoe  
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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Aday-Amoakoh *et al.*

Examiner: Andujar, Leonardo

Serial No.: 09/827,014

Art Unit: 2826

Filed: 4/5/01

For: **ECONOMICAL HIGH DENSITY CHIP CARRIER****FAX RECEIVED**Commissioner for Patents  
Washington, D.C. 20231

APR 07 2003

TECHNOLOGY CENTER 2800

Sir:

This paper is being filed in response to a Final Office Action dated February 26, 2003 in connection with the above-identified application. Reconsideration and allowance are respectfully requested in view of the Amendments and Remarks below.

**Amendment****In the Claims:**


Claims 1-6, 9 and 20 have been amended prior to the present office action response. No claims are amended herein in the present office action response. Currently pending claims 1-9 and 20 for consideration by the Examiner are as follows:

1. (PREVIOUSLY AMENDED) An electronic structure comprising:

a substrate having a dielectric layer between a first metal layer and a second metal layer, the second metal layer being disposed above the first metal layer, the first metal layer having a

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<b>CERTIFICATE OF TRANSMISSION BY FACSIMILE (37 CFR 1.8)</b>			<b>Docket No.</b> <b>END920000149US1</b>
Applicant(s): <b>Adae-Amoakoh et al.</b>			
<b>Serial No.</b> <b>09/827,014</b>	<b>Filing Date</b> <b>4/5/2001</b>	<b>Examiner</b> <b>Andujar, Leonardo</b>	<b>Group Art Unit</b> <b>2826</b>
Invention: <b>ECONOMICAL HIGH DENSITY CHIP CARRIER</b>			
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I hereby certify that this <u>Amendment (8 pages-last page Appendix A)</u> (Identify type of correspondence)			
is being facsimile transmitted to the United States Patent and Trademark Office (Fax. No. <u>703-308-7722</u> )			
on <u>4/7/2003</u> (Date)			
<b>Kim Dwileski</b> (Typed or Printed Name of Person Signing Certificate)			
 (Signature)			
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